



Ai-SG01 Specification

Version V1.0.0

Copyright ©2025

Document resume

[illegible]

Content

1. Product Overview	4
1.1. Characteristic	5
2. Main parameters	6
2.1. Static electricity requirement	6
2.2. Electrical characteristics	7
2.3. RF Performance	7
3. Appearance Dimensions	8
4. Pin Definition	9
5. Schematic	10
6. Design Guidance	11
6.1. Application Guidance Circuit	11
6.2. Recommended PCB package size	12
6.3. Antenna Layout Requirements	12
6.4. Power supply	12
6.5. GPIO	13
7. Storage conditions	14
8. Reflow welding curve diagram	14
9. Product Packaging Information	15
10. Contact us	15
Disclaimer and copyright notice	16
Notice	16
Important Notice	17

1. Product Overview

Ai-SG01 is an ultra-high-performance RF front-end module based on PANCHIP's next-generation PAN3210 RF chip, designed for the **Internet of Things, short-range wireless communications, and Industry 4.0 wireless sensor networks**. Its core advantage lies in its **extremely small package, achieving extreme RF performance**. By optimizing the coordinated design of the power amplifier, low-noise amplifier, filter, and peripheral matching network, it achieves high output power, low loss, and strong anti-interference capabilities, while also meeting mainstream global regulatory certifications.

The Ai-SG01 module supports flexible multi-band configuration (420-445MHz and 470-510MHz optional) and is suitable for scenarios with dual requirements for size and performance, such as wireless sensors, smart home terminals, industrial monitoring, and medical wearables.

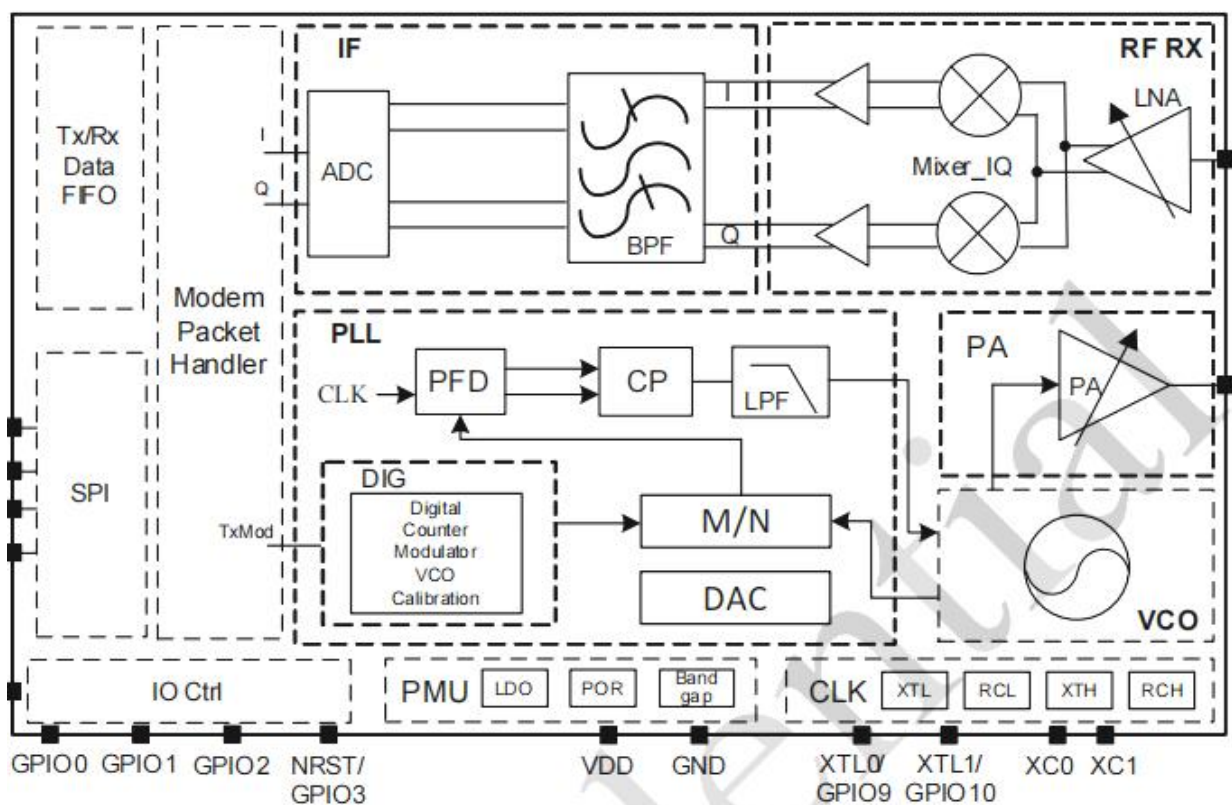


Figure 1 Main chip architecture diagram

1.1. Characteristic

- Ultra-compact 12mm*13mm*2.4mm SMD-16 package
-)Operating frequency bands: 420-445MHz, 470-510MHz (band selectable, switchable via software and hardware configuration)
- Maximum transmit power of the module reaches 20dBm (100mW), supporting DPC (-20 to 20dBm) in 1dB increments
- Module receive sensitivity: -121dBm @ 2.4kbps, -107dBm @ 50kbps, -103dBm @ 100kbps, -94dBm @ 500kbps
- Low spurious design: Harmonic suppression $\leq -60\text{dBc}$ (2nd/3rd harmonics) at full load transmission, meeting CE, FCC, and other regulations.
- Low ACPR design: Built-in predistortion engine achieves $\leq -55\text{dBc}$ (50kbps FSK) at +20dBm output
- The module's default data rate range is 2 to 500kbps, with optional settings of 2kbps to 2Mbps and 2kbps to 4Mbps (three speed ranges, switchable via software and hardware configuration)
- Industrial-grade standard design, operating temperature range -40°C to 85°C (optional -40°C to 105°C)
- Rich interfaces, including support for 4-wire SPI, 3-wire SPI, and 5 GPIO
- Wide voltage supply, supports 1.8V to 3.8V (LDO mode)
- Sleep current as low as 300nA
- Special features: Supports RSSI and LQI, automatic frequency control (AFC), built-in 32K RC clock and external 32K crystal oscillator, duty cycle receive and transmit, and automatic ACK
- Supports whitening, FEC, CRC, Manchester code, and other functions
- Stamp hole interface, facilitating integration

2. Main parameters

Table 1 Description of the main parameters

Model	Ai-SG01
Package	SMD-16
Size	12.0*13.0*2.4 (mm)
Antenna	External antenna
Frequency	420-445MHz or 470-510MHz
Operating temperature	-40~85°C
Storage temperature	-40 °C ~ 125 °C , < 90%RH
Power supply	Support 1.8 ~ 3.8V power supply (LDO mode), supply current ≥ 500mA
Interface	SPI
IO	5
SPI rate	Default 4.5MHz

2.1. Static electricity requirement

Ai-SG01 is an electrostatically sensitive device and requires special precautions when handling. These should generally be applied to ESD-sensitive components. Proper ESD handling and packaging procedures must be employed throughout the handling, transportation, and operation of any application incorporating the Ai-SG01 module. Do not touch the module with your hands or use a non-antistatic soldering iron for soldering, as this may damage the module.



Figure 2 ESD preventive measures

2.2. Electrical characteristics

Table 2 Electrical characteristics table

Parameters		Name	Min.	Typical value	Max.	Unit
Internal LDO mode supply voltage		3V3	1.8	3.3	3.8	V
Power supply	Full load mode (TX:20dBm)	433MHz		116		mA
		470MHz		100		mA
		490MHz		110		mA
		510MHz		115		mA
	Sleep			800		nA
	Deep Sleep			300		nA

2.3. RF Performance

Table 3 RF performance

Output Power				
Mode	Min.	Typical	Max.	Unit
433MHz		20		dBm
470MHz		20		dBm
490MHz		20		dBm
510MHz		20		dBm
Receive Sensitivity				
Mode	Min.	Typical	Max.	Unit
433.9MHz@50kbps		-108		dBm
470.9MHz@50kbps		-108		dBm
490.9MHz@50kbps		-108		dBm
505.9MHz@50kbps		-108		dBm

3. Appearance Dimensions

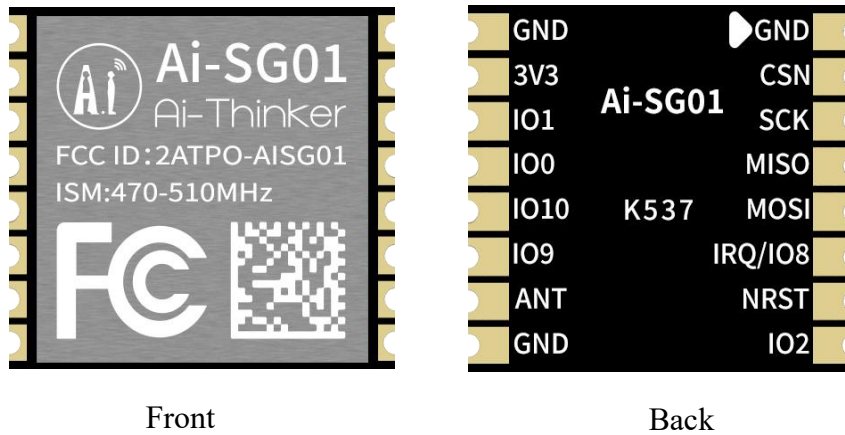


Figure 3: Appearance of the 470-510MHz module (rendering is for reference only, the actual product shall prevail)

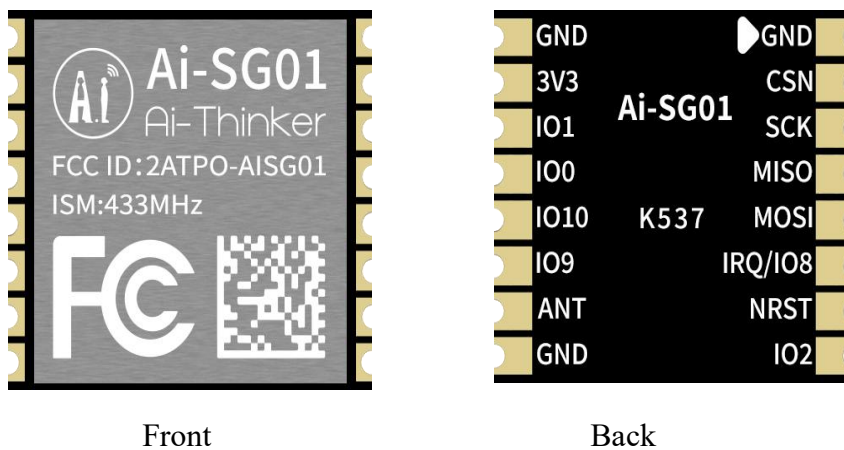


Figure 4: Appearance of the 433MHz module (rendering is for reference only, the actual product shall prevail)

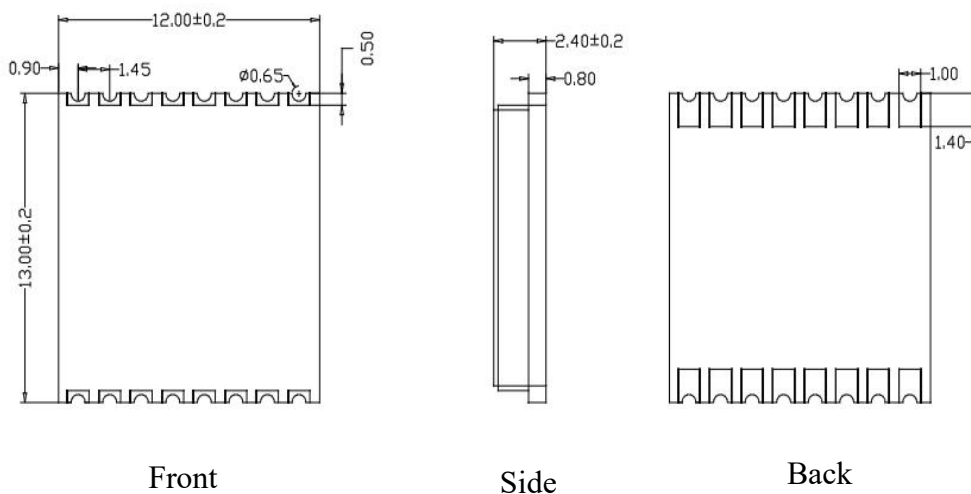


Figure 5 Dimensions

4. Pin Definition

Ai-SG01 module has a total of 16 pins, as shown in the pin diagram. The pin function definition table is the interface definition.

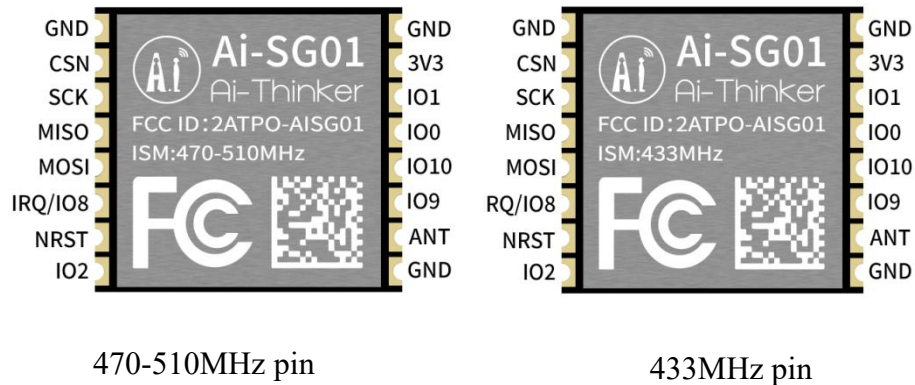


Figure 6 Pin diagram

Table 4 Pin function definition table

No.	Name	Function
1	GND	GND
2	CSN	SPI interface chip select input
3	SCK	SPI interface clock input
4	MISO	SPI interface MISO data output
5	MOSI	SPI interface MOSI data input
6	IRQ/IO8	Interrupt signal pin, directly connected to chip GPIO8
7	NRST	Chip hardware reset pin
8	IO2	Digital IO, software configurable, directly connected to chip GPIO2
9	GND	GND
10	ANT	RF signal input/output, connects to a 50Ω antenna
11	IO9	Digital IO, software-configurable, directly connected to the chip: GPIO9
12	IO10	Digital IO, software-configurable, directly connected to the chip: GPIO10
13	IO0	Digital IO, software-configurable, directly connected to the chip: GPIO0
14	IO1	Digital IO, software-configurable, directly connected to the chip: GPIO1
15	3V3	Module power supply, LDO mode, voltage range: 1.8V~3.6V
16	GND	GND

Figure 7 Module schematic

6. Design Guidance

6.1. Application Guidance Circuit

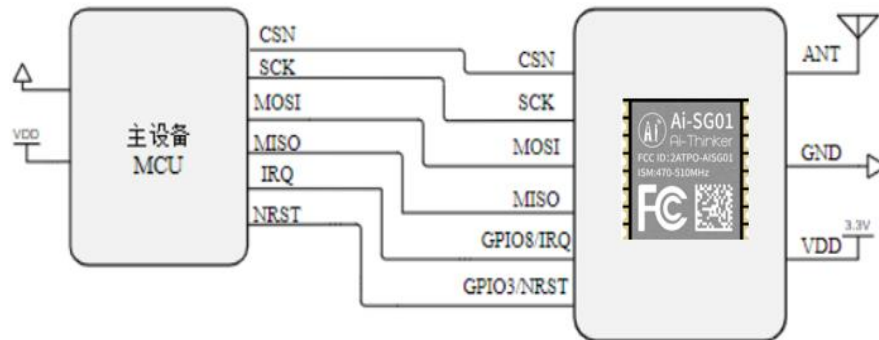


Figure 8 Application guidance circuit

- If the communication interface uses 3-wire SPI, the MISO pin can be left unconnected.
- The VDD power supply in the figure is typically 3.3V. The module's power supply range is as follows:
 - a. In LDO mode, 1.8V to 3.8V
 - b. In DCDC mode, 2.0V to 3.8V
- Supply current > 500mA

6.2. Recommended PCB package size

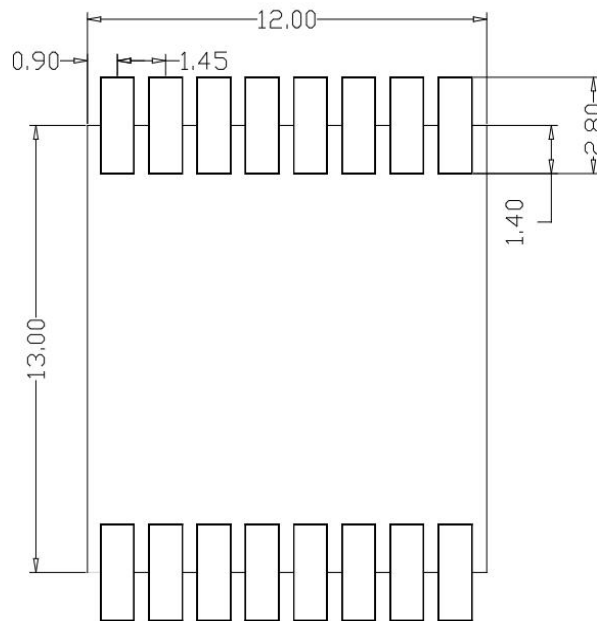


Figure 9 Recommended PCB package size

6.3. Antenna Layout Requirements

- This module requires an external antenna. The following two methods are recommended for antenna installation on the motherboard:

Solution 1: Place the module on the edge of the motherboard, with the antenna extending beyond the edge.

Solution 2: Place the module on the edge of the motherboard, with a hollowed-out area at the antenna location.

- To ensure optimal antenna performance, avoid placing metal objects around the antenna and keep it away from high-frequency components.

6.4. Power supply

- Recommended VDD voltage: 3.3V, peak current: 500mA or higher.
- Recommended power supply: LDO. If using a DC-DC converter, ripple should be kept within 30mV.
- In the DC-DC converter circuit, it is recommended to reserve space for dynamic response capacitors to optimize output ripple under large load fluctuations.

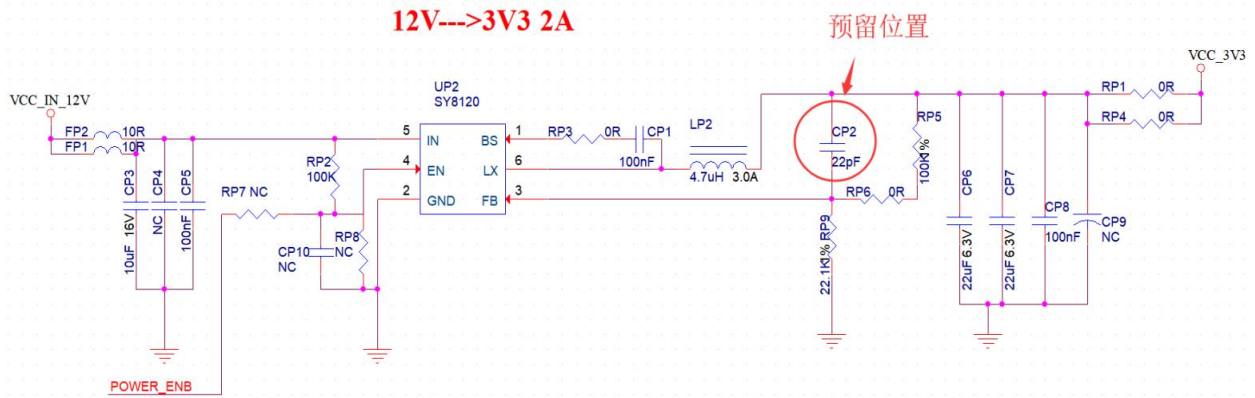


Figure 10 DC-DC buck circuit diagram

6.5. GPIO

- The module's external IO ports are connected. If you need to use them, it's recommended to connect a 10-100 ohm resistor in series with the IO ports. This can suppress overshoot and stabilize the voltage levels on both sides. This helps with both EMI and ESD.
- For pull-up and pull-down configurations on specific IO ports, please refer to the datasheet, as this will affect the module's startup configuration.
- If the module's IO ports are 3.3V, adding a level shifter is necessary if the voltage levels of the main controller and module's IO ports don't match.
- If the IO ports are directly connected to peripheral connectors or pin headers, it's recommended to place ESD devices near the terminals along the IO port traces.

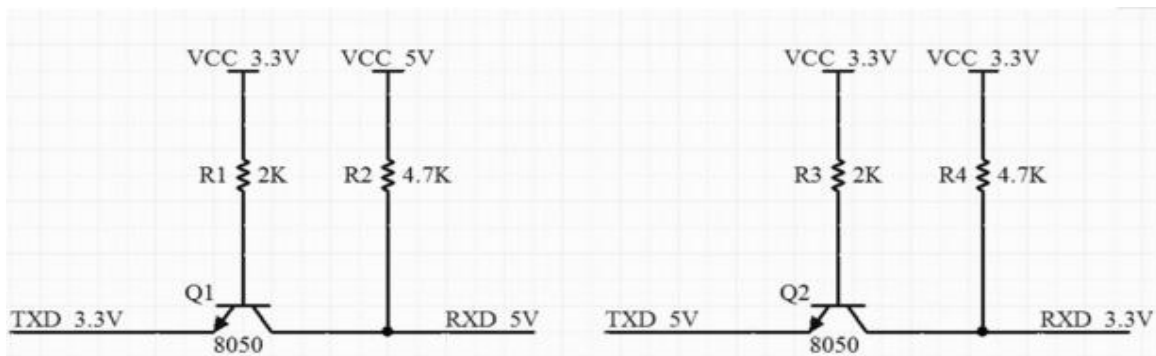


Figure 11 Level conversion circuit

7. Storage conditions

Products sealed in moisture-proof bags should be stored in a non-condensing environment at temperatures below 40°C/90% RH.

The module's Moisture Sensitivity Level (MSL) is 3.

After unsealing the vacuum bag, the product must be used within 168 hours at 25±5°C/60% RH. Otherwise, it must be baked before re-use.

8. Reflow welding curve diagram

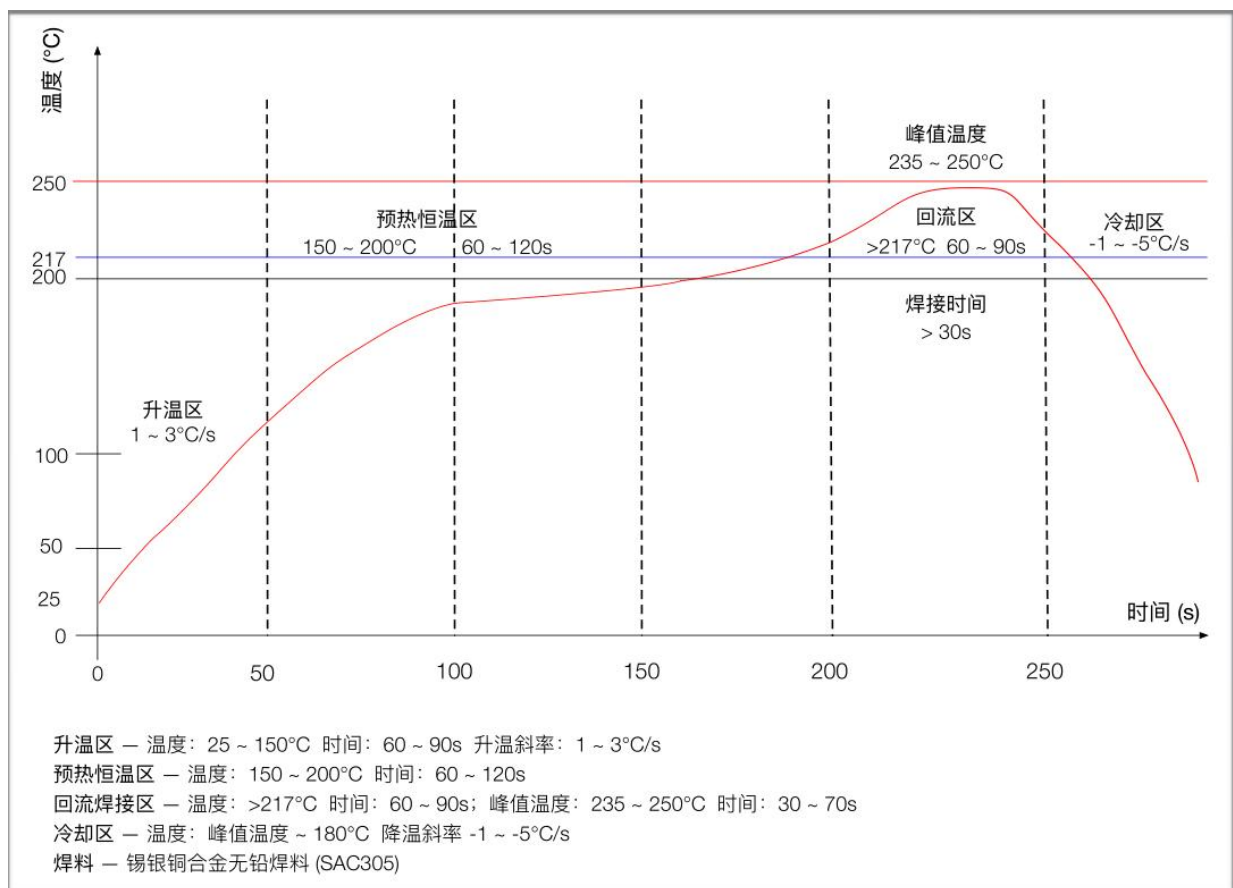


Figure 12 Reflow curve

9. Product Packaging Information

Ai-SG01 modules are packaged in tape, 1000 pieces per tray. As shown in the following figure:



Figure 13 Packaging tape diagram

10. Contact us

[Ai-Thinker official website](#)

[Office forum](#)

[Develop DOCS](#)

[LinkedIn](#)

[Tmall shop](#)

[Taobao shop](#)

[Alibaba shop](#)

[Technical support email: support@aithinker.com](#)

[Domestic business cooperation: sales@aithinker.com](#)

[Overseas business cooperation: overseas@aithinker.com](#)

Company Address: Room 403,408-410, Block C, Huafeng Smart Innovation Port, Gushu 2nd Road, Xixiang, Baoan District, Shenzhen.

Tel: +86-0755-29162996



WeChat Mini program



WeChat official account

Disclaimer and copyright notice

The information in this article,including the URL address for reference,is subject to change without notice.

The document is provided"as is"without any guarantee responsibility,including any guarantee for merchantability,suitability for a specific purpose,or non-infringement,and any guarantee mentioned elsewhere in any proposal,specification or sample.This document does not bear any responsibility,including the responsibility for infringement of any patent rights arising from the use of the information in this document.This document does not grant any license for the use of intellectual property rights in estoppel or other ways,whether express or implied.

The test data obtained in the article are all obtained from Ai-Thinker's laboratory tests,and the actual results may vary slightly.

All brand names,trademarks and registered trademarks mentioned in this article are the property of their respective owners,and it is hereby declared.

The final interpretation right belongs to Shenzhen Ai-Thinker Technology Co.,Ltd.

Notice

Due to product version upgrades or other reasons,the contents of this manual may be changed.

Shenzhen Ai-Thinker Technology Co.,Ltd.reserves the right to modify the contents of this manual without any notice or prompt.

This manual is only used as a guide.Shenzhen Ai-Thinker Technology Co.,Ltd. makes every effort to provide accurate information in this manual.However, Shenzhen Ai-Thinker Technology Co.,Ltd. does not guarantee that the contents of the manual are completely free of errors.All statements and information in this manual And the suggestion does not constitute any express or implied guarantee.

Important Notice

Ai-Thinker provides technical and reliability data (including datasheets), design resources (including reference designs), application or other design advice, web tools, safety information, and other resources (hereinafter referred to as "these resources") "as is" with all faults and without warranty of any kind, either express or implied, including but not limited to warranties of merchantability, fitness for a particular purpose, or non-infringement of any third party intellectual property rights. Ai-Thinker specifically disclaims any liability for consequential or incidental damages arising out of or in connection with the application or use of any of its products and circuits.

Ai-Thinker reserves the right to make changes to the information published in this document (including but not limited to specifications and product descriptions) and any of its products covered by this document without prior notice. This document automatically supersedes and replaces all information provided in previous versions of documents with the same part number.

These resources are intended for use by experienced developers designing with Ai-Thinker products. You will be solely responsible for the following: (1) selecting appropriate Ai-Thinker products for your application; (2) designing, verifying, and operating your application and product throughout its lifecycle; and (3) ensuring that your application meets all applicable standards, specifications, and laws, as well as any other functional safety, information security, regulatory, or other requirements. Ai-Thinker authorizes you to use these resources solely for the development of applications for the Ai-Thinker products described in these resources. Without the permission of Ai-Thinker, no entity or individual may excerpt or copy these resources in part or in whole, and may not disseminate them in any form. You have no right to use any other Ai-Thinker intellectual property or any third-party intellectual property. You shall fully indemnify Ai-Thinker and its representatives for any claims, damages, costs, losses, and liabilities arising from the use of these resources, and Ai-Thinker shall not be liable for any such claims. Products provided by Ai-Thinker are subject to Ai-Thinker's terms of sale or other applicable terms accompanying the Ai-Thinker products. Ai-Thinker's provision of these resources does not extend or otherwise alter the warranties or warranty disclaimers applicable to the product release.